

**REMARKS/ARGUMENTS**

Favorable reconsideration of this application, as presently amended and in light of the following discussion, is respectfully requested.

Claims 1-6 are pending.

In the Official Action, Claims 1-6 were rejected under 35 U.S.C. § 112, 1<sup>st</sup> para., as failing to comply with the written description requirement, the Official Action finding that there is insufficient written description in the original specification for the recitation of “after selectively irradiating [sic: “irradiating”] ... connected to the electrode (claim 1, lines 10-12).”

Applicants respectfully traverse the outstanding ground for rejection, because in Applicants’ view, Applicants’ original specification clearly complies with the 35 U.S.C. § 112, 1<sup>st</sup> para., written description requirement, for the reasons next discussed.

Pending Claim 1 recites:

1. An electronic device connecting method comprising:

mounting an electrode of an electronic device closely on a sheet-like porous member having pores, the porous member having a photosensitive layer formed on an inner surface of pores, the photosensitive layer producing or eliminating an ion exchange group by irradiation with energy beams on the inner surface of the pores;

selectively irradiating a predetermined region of the porous member, on which the electronic device is mounted, with energy beams thereby exposing the photosensitive layer to form a latent image in an irradiated or non-irradiated portion of the porous member, the predetermined region including a portion close to the electrode;

**after said selectively irradiating, filling pores in the latent image of the porous member with a conductive material to simultaneously form a wiring portion and a via contact connected to the electrode; and**

bonding the porous member, in which the wiring portion and the via contact is formed by said filling, to the electronic device. (emphasis added)

Applicants refer the Examiner to page 35, lines 7-16 and page 36, lines 4-33 of Applicants specification for support of the claimed feature at issue. For example, the disclosure at page 35, lines 7-16 states:

... As shown in FIGS. 1d and 2d, a conductive material or its precursor is selectively filled in holes of the exposed or unexposed portion of the porous sheet 1 after pattern exposure **to form package wiring portions, such as wiring portions 5b and via contacts 6b**. The porous sheet is impregnated with the filled conductive material so that the conductive material is integrated with the porous structure. ...<sup>1</sup> (emphasis added)

... If the porous sheet is irradiated with energy beams so that the energy beams pass through the porous sheet in thickness direction, it is possible to form a via portion being a conductive pattern passing through the sheet in thickness directions. By the same method, it is also possible to form a wiring portion passing through the sheet in thickness direction. If only the vicinity of the surface of the porous sheet is irradiated with energy beams, it is possible to form wiring, pad and ground on the surface of the porous sheet. In addition, if the sheet is three-dimensionally irradiated with energy beams, **it is possible to make the multilayer structure of wiring and via portions in a single porous sheet**. ...<sup>2</sup> (emphasis added)

The quoted portions of the specification are believed to provide clear support for the claimed feature “after said selectively irradiating, filling pores in the latent image of the porous member with a conductive material to simultaneously form a wiring portion and a via contact connected to the electrode.” First, it is acknowledged that these cited portions do not specifically include the work “simultaneously,” but simultaneous formation of wiring portions and via contacts is believed to be a necessary consequence of the fact that the “porous sheet is impregnated with the filled conductive material so that the conductive material is integrated with the porous structure.” In other words, impregnation of the porous sheet with the conductive material simultaneously generates formation of conductive

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<sup>1</sup> Specification, page 35, lines 7-16.

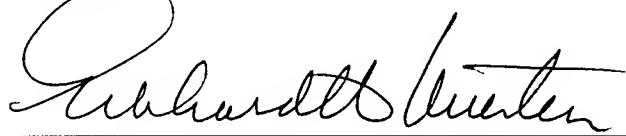
<sup>2</sup> Id., page 36, lines 4-16.

elements, be it wiring portions or via contacts, in regard to the pores which are impregnated. As the disclosure is not limited to impregnation of only wiring portions or of only via contacts, it is clear that the impregnation of the porous sheet in which wiring portions or via contacts are to be formed, results in simultaneous formation of wiring portions and via contacts. While Applicants are not opposed to amending the specification accordingly, such amendment is not deemed necessary insofar as the quoted language clearly supports the claim language. If the Examiner disagrees, the Examiner is requested to propose amendment by Examiner's amendment, or otherwise clarify the basis for disagreement. For the present, the outstanding ground for rejection under 35 U.S.C. §112, 1<sup>st</sup> para., is traversed.

Accordingly, there being no further issues outstanding, the pending claims are believed to be in condition for formal allowance and an early and favorable action to that effect is respectfully requested.

Respectfully submitted,

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